

ROC chip status

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Orsay Micro Electronics Group Associated

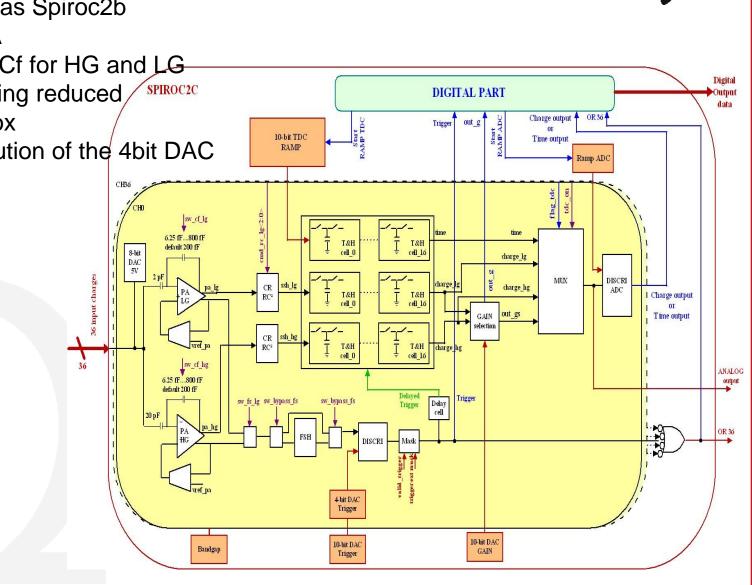
Many measurements are still on going on test board and at system level to characterize in detail the ROC chips before submitting 3rd generation chips

- HARDROC3: will be submitted in Feb 2013
- Many measurements performed on SKIROC2 (see Stephane's talk) and on SPIROC2B and 2C
- SKIROC2 and SPIROC2B/2C are the same except for the input preamplifier: same fast and slow channel, same digital part.

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SPIROC2C

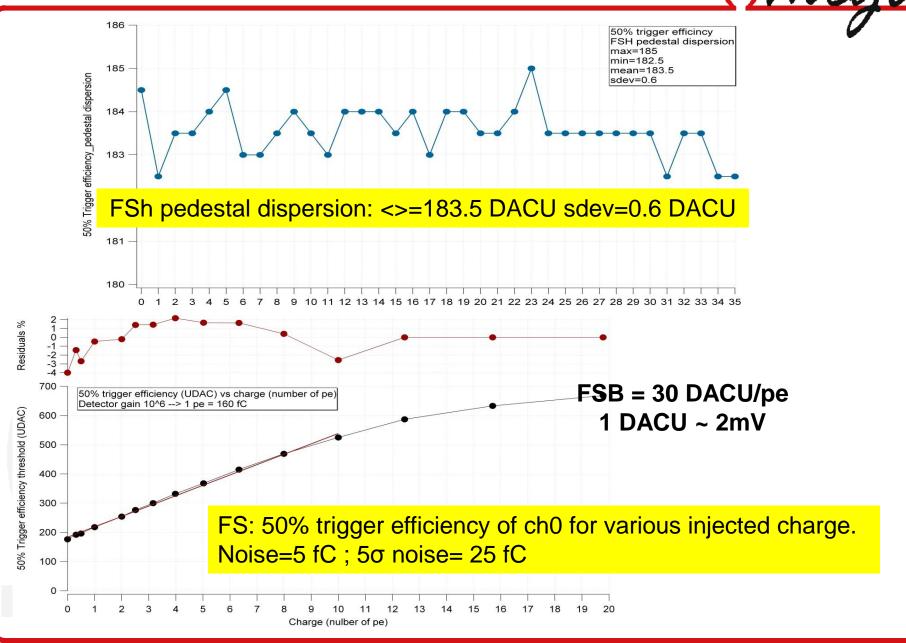
- Same pinout as Spiroc2b
- New input PA
- Independant Cf for HG and LG
- HG/LG coupling reduced,
- New delay box
- Better distribution of the 4bit DAC



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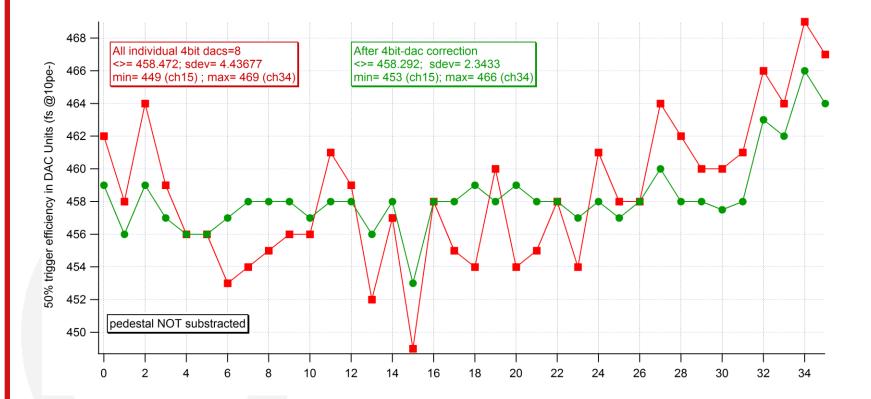
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SPIROC2C: FS Uniformity (HG=200; LG=100) mega



SPIROC2C: 4-bit DAC channel wise tuning

FS@ 10 pe injected

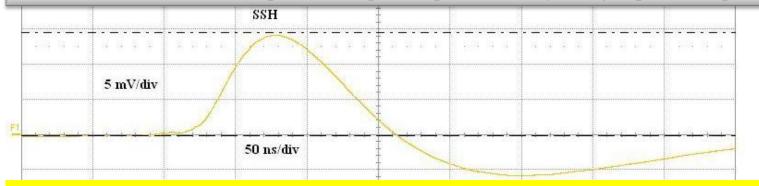


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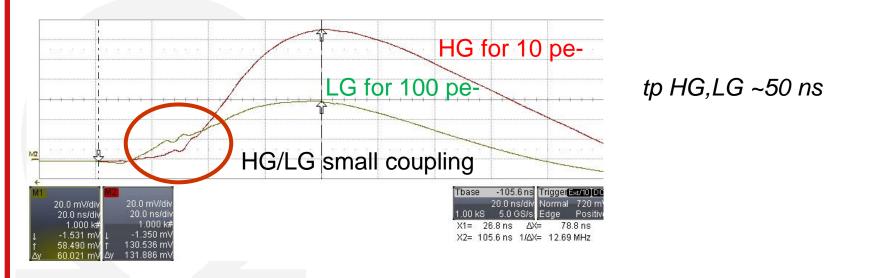
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SPIROC2C: HG and LG slow shapers

PA_HG=bit100 x 6.25fF= $625fF => G=20pF/625fF= 32 => dyn range up to 100 pe-PA_LG=bit200x6.25 fF=1.25pF => G=2pF/1.25pF= 1.6 => dyn range up to 1500 pe-$

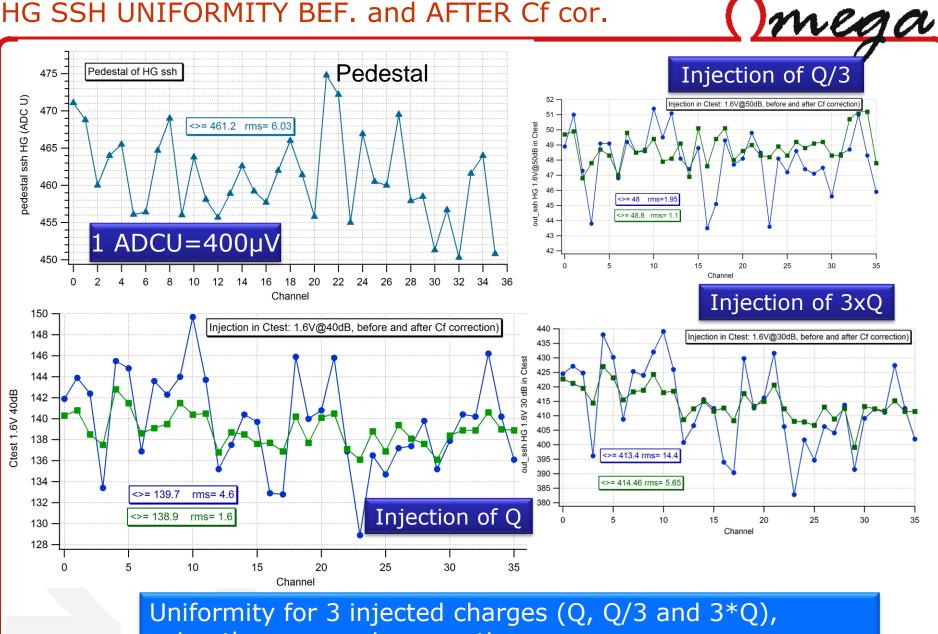


HG SSh: Vmax= 14.65 mV/pe (1pe=160 fC) RMS noise = $1.2mV = SNR \sim 12$



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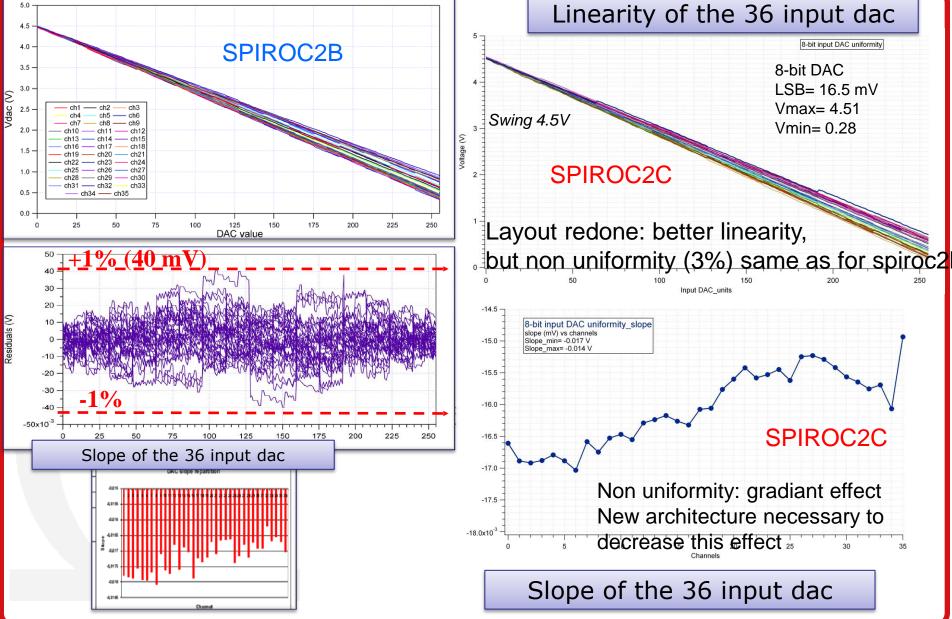
HG SSH UNIFORMITY BEF. and AFTER Cf cor.

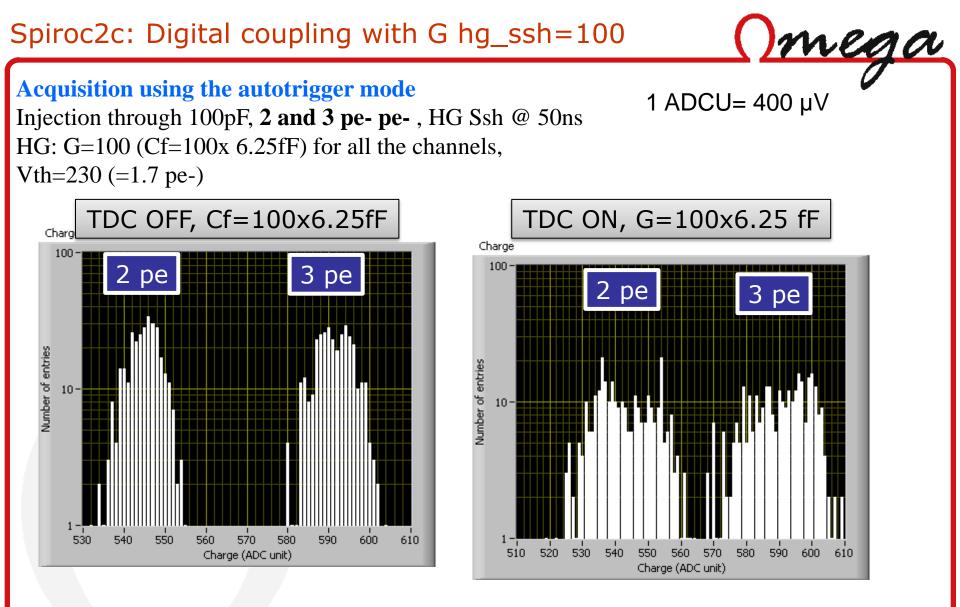


using the same gain correction

8-bit input DAC linearity

<u> Meaa</u>

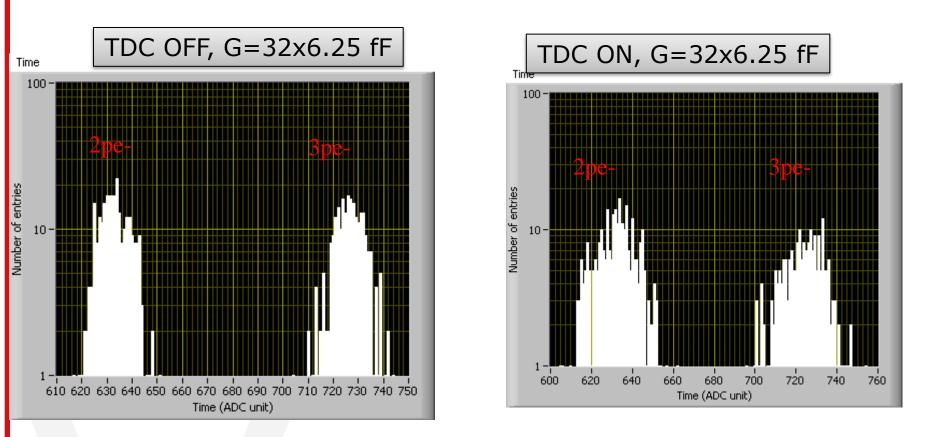




TDC => digital coupling in spiroc2c through the substrate (NMOS preamp connected to gnd) There is no digital coupling in spiroc2b (PMOS transistor connected to vdd)

Digital coupling in Spiroc2c with G hg_ssh=32

Injection through 100pF, **2 and 3 pe- HG with G=32** (**32x6.25fF**) for all the channels, ssh@50n Vth=260 (~1pe-)

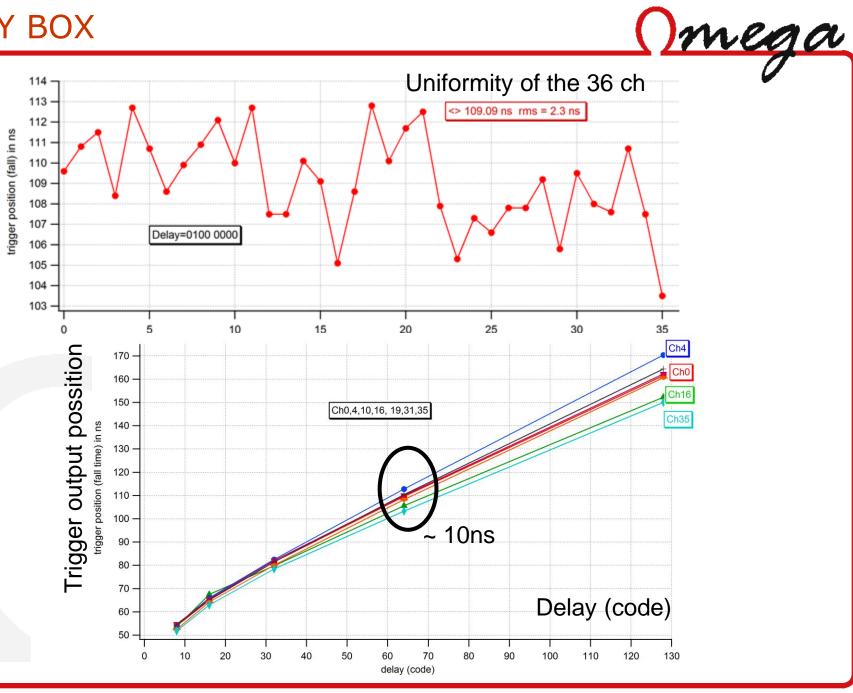


TDC coupling in Spiroc2c doesn't prevent to distinguish 2 and 3 pe-

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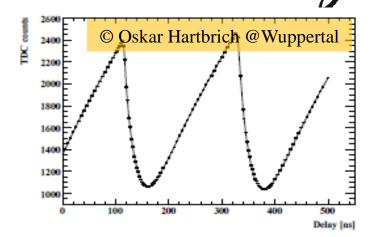
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DELAY BOX

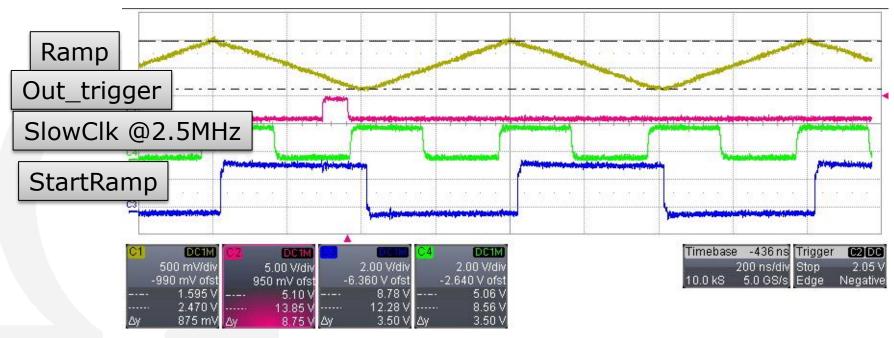


SPIROC 2c: TDC

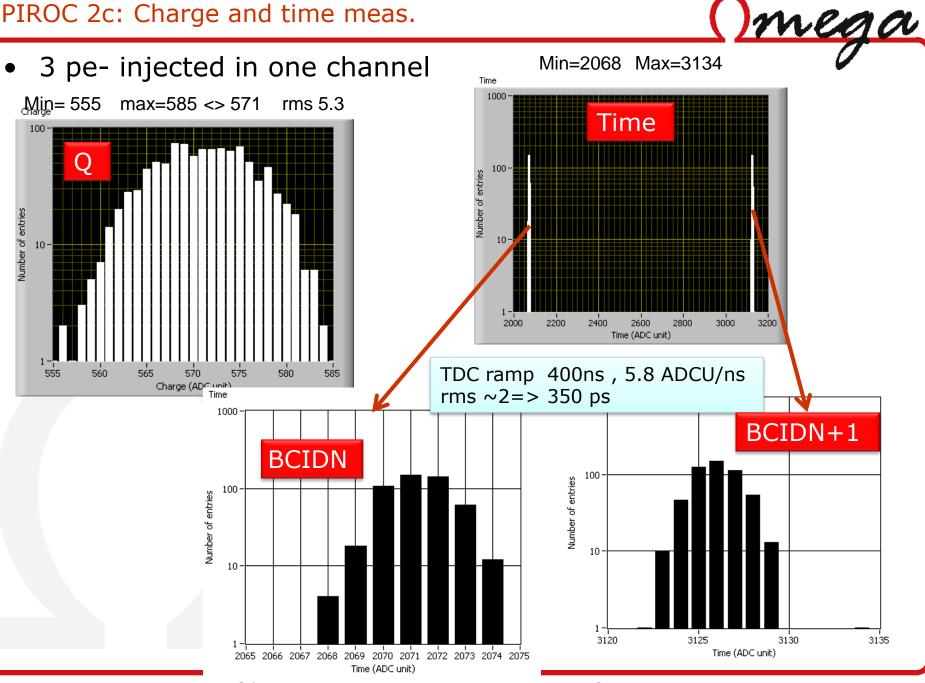
- SPIROC2B TDC: Dead time due to the mutiplexer
- SPIROC2C TDC
 - To decrease dead time during transition
 => alternation of a rising and a falling ramp implemented
 - Conservative modification

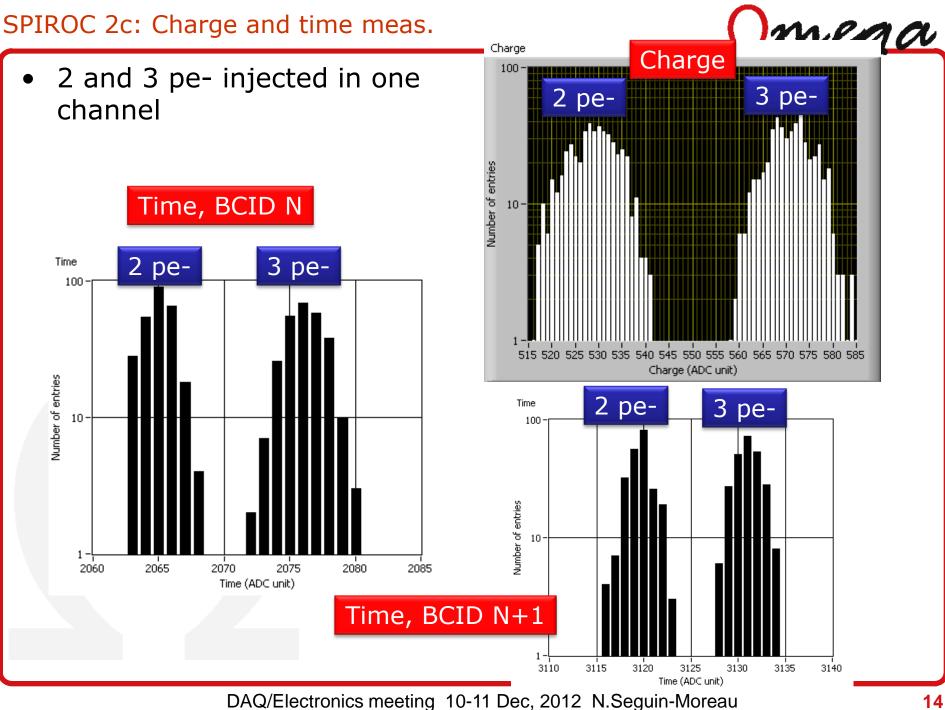


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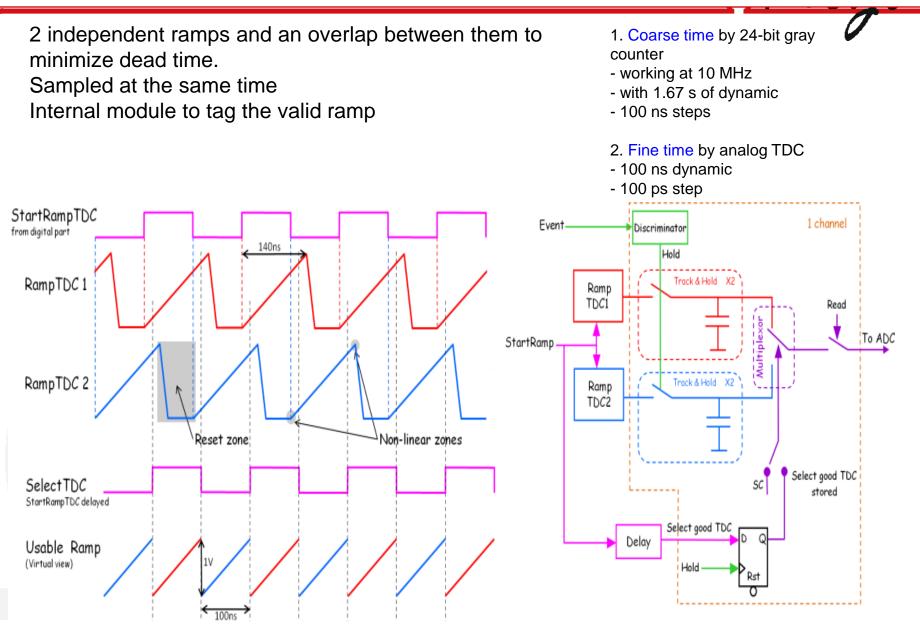
SPIROC 2c: Charge and time meas.





TDC for SPIROC3: PARISROC TDC ramp ?

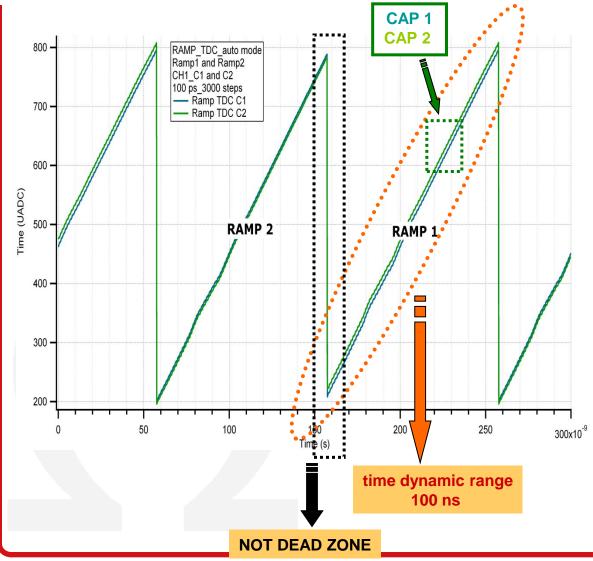
tested by IPNO team



PARISROC TDC ramp

Reconstruction of the ramp from the time values saved in the analog memory and converted by the ADC (10-bit).

The validation of the good ramp is made automatically



	Second version		
Time dynamic range	100 ns		
"Blind zone"	0		
linear zone	100 ns		
Ramp 1 linear	±1ns		
Ramp 2 linear	±1ns		

SPIROC3

Complex chip (internal SCA, ADC, TDC)

- Many bugs corrected + new features in SPIROC2c:
 - HG/LG coupling
 - Independent Cf for HG and LG
 - 4-bitsDAC
 - Delay box
 - Rate dependency
 - Pedestal shift (to be checked by DESY)
 - Zero events
- Still improvements to be done:
 - 8-bit input DAC: to be improved
 - NMOS or PMOS preamp? = digital coupling vs pedestal shift

AIDA

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- TDC
- HBU with spiroc2c to be tested
- I2C link: feedback from HR3 necessary

HARDROC3

- First of the "3rd generation ROC chip" to be submitted
- independent channels, one register/channel, I2C link for SC parameters(@IPNL), triple voting, circular memory, temperature sensor
- Digital part finished in July 2012
- Analog part: No major modifications in the analog part. Extension of the dynamic range to set Vth0=100fC Vth1=5pC and Vth2 > 15 pC
- Die size ~30 mm2
- <u>Submission in FEB 2013</u>=> reception in June 2013.

Next: SPIROC3 or SKIROC3 ?

- Still many tests to be done at the system level/testbeam
- Hardroc3 test feedback necessary before submitting Spiroc3/skiroc3
- Spiroc3= 36 channels, 8.5 x 5 mm2 => 42.5 k€ in MPW run
- Skiroc3= 64 channels, 8.5x9.5 mm2 => 81 k€ in a MPW run => dedicated run mandatory
- SPIROC3 and SKIROC3 in Feb 2014 in a dedicated run (AIDA, CALICE and other partners)

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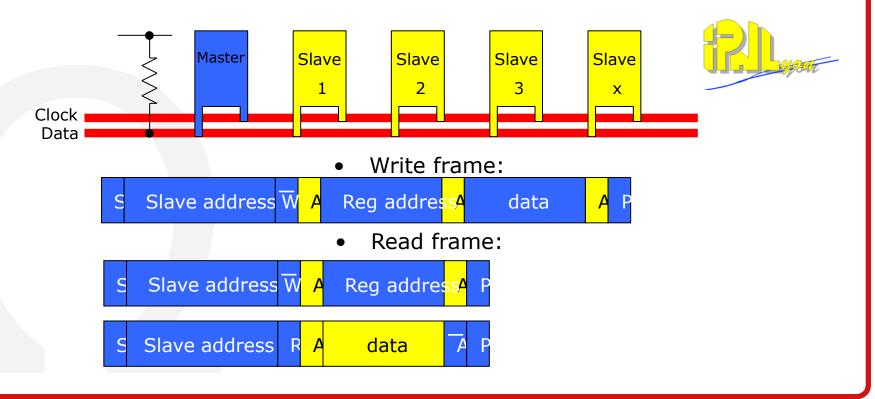


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3Gen ROC chips: common features

- Slow control parameters:
 - Backward compatibility with 2Gen ROC chips slow control
 - Use of classical shift register slow control
 - Embedded I2C
 - 7-bit address + 1 general call address (127 chips can be addressed)
 - Access port doubled
 - Bidirectional data line with open collector (Driver will be the same as Dout)
 - Read back capability of SC bits (non destructive)

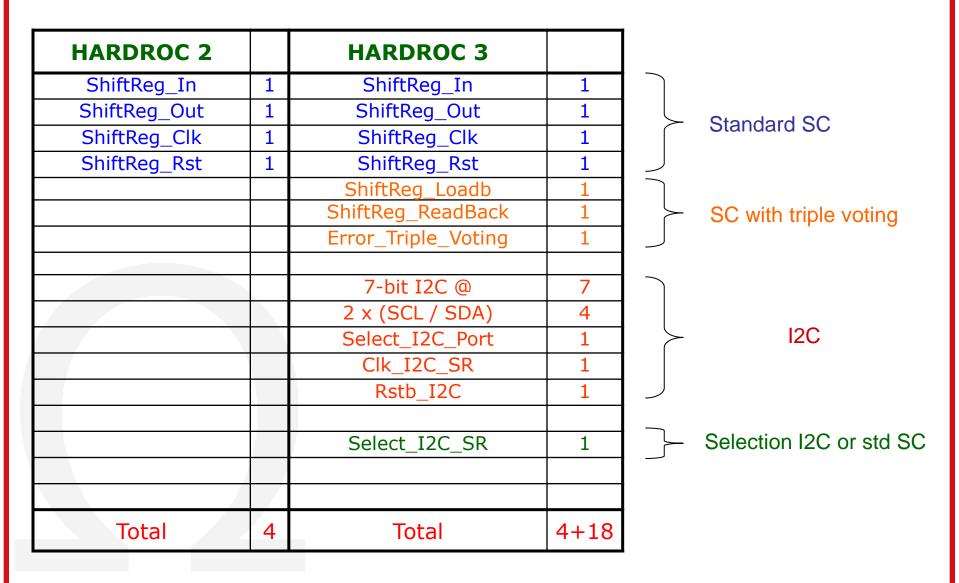


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3Gen ROC chips: common features

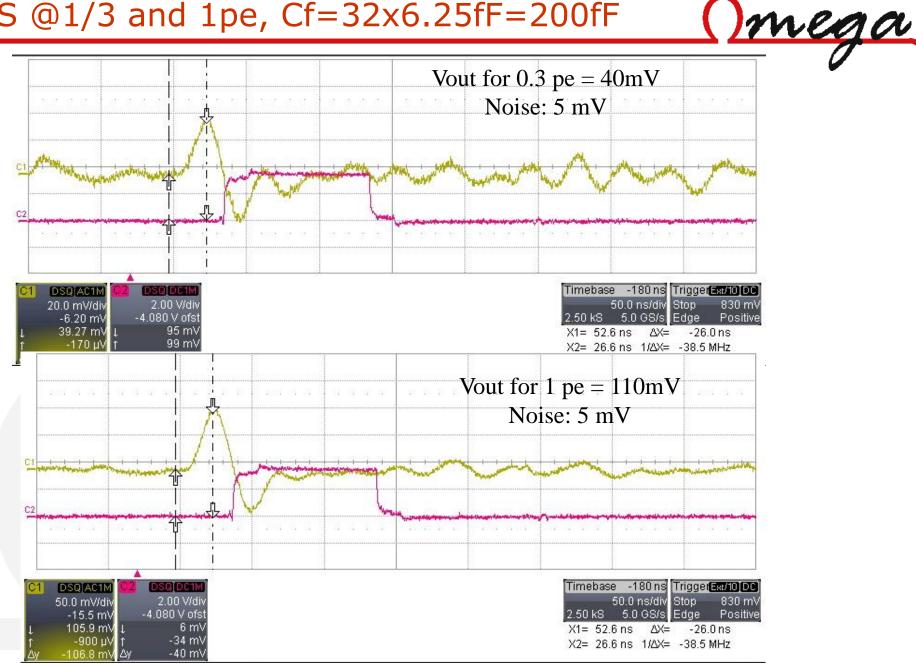
• Extra pin needed for I2C / SC:



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FS @1/3 and 1pe, Cf=32x6.25fF=200fF



« Pedestal shift » due to coupling on Vdda_pa on spiroc2b

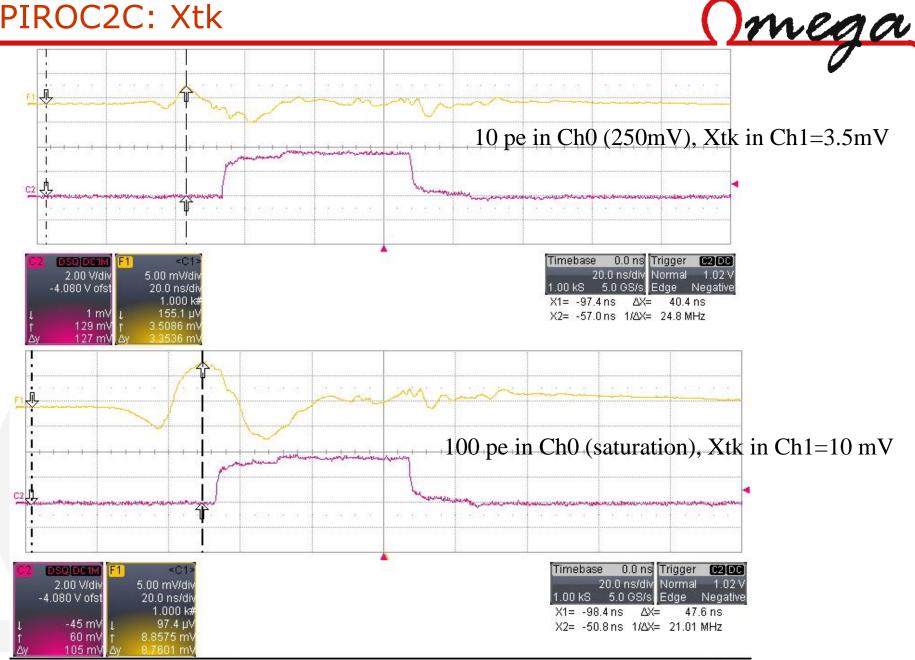
Spiroc2c: Injection of 10, 100, 300 and 1000pe- in ch0 and measurement of the charge (HG) seen on the neighbours (all preamp on but all discris masked except of ch<0>:

	10pe-	100pe-	300pe-	1000pe-
Ch<0>	950 UADC	3500	3500	3500
Ch<1>	470	470	450	450
Ch<2>	470	460	440	440
Ch<3>	460	463	446	446
Ch<20>	460	457	450	450
Ch<35>	455	457	455	455

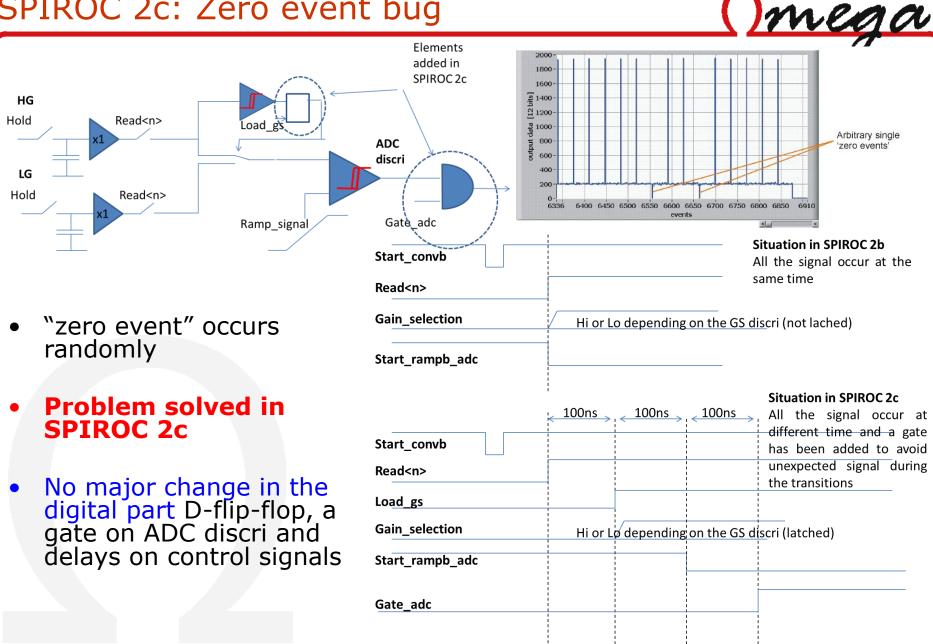
When discris of the other channels are ON = > we measure Xtk in the neighbours

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SPIROC2C: Xtk



SPIROC 2c: Zero event bug



SPIROC2C: New Delay box

